

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : SCHREDL et al.
Serial No : 10/020,594
Confirm. No. : 7149
Filed : December 13, 2001
For : CONTACT STRUCTURE FOR...
Art Unit : 1793
Examiner : Kevin P. Kerns
Dated : January 28, 2009

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

The following references have been cited in a Japanese Office Action dated July 9, 2008 and/or cited in a Japanese Office Action dated December 24, 2008.

- JP 09-148693 discloses a flip chip mounting board and manufacture thereof. The reference has been cited in both Office Actions. No translation is available at this time, however, attached is an English language abstract.

- JP 04-037147 discloses a mounting of semiconductor chip. The reference has been cited in both Office Actions. No translation is available at this time, however, attached is an English language abstract.

- JP 09-134934 discloses a semiconductor package and semiconductor device. The reference has been cited in both Office Actions. No translation is available at this time, however, attached is an English language abstract.

- JP 10-153270 discloses a wiring board with joining bump. The reference has been cited in the Office Action dated December 24, 2008. No translation is available at this time, however, attached is an English language abstract.

Consideration of the above references is requested.

Respectfully submitted
for Applicant,



By: _____
John James McGlew
Registration No. 31,903
McGLEW AND TUTTLE, P.C.

JJM:tf
70408RCE4-8

Enclosed: PTO/SB/08a Form
copy of (4) References and (4) English Abstracts

DATED: January 28, 2009
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SHOULD ANY OTHER FEE BE REQUIRED, THE PATENT AND TRADEMARK OFFICE IS HEREBY REQUESTED TO CHARGE SUCH FEE TO OUR DEPOSIT ACCOUNT 13-0410.